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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier		User Part Number				
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		BZX84-B16-Q Part Description				
		SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects
			TEST Pre- and Post-Stress			
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	1514	64430	0
# B1	HTRB	MIL-STD-750-1 M1038 Method A Tj = Tjmax, VR = 80 % of rated reverse voltage	1000 hours	250	11400	0
# B1b	SSOP Steady State Operational	MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet reverse current	1000 hours	44	1920	0
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0
# A3 or	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	—96 hours	311	14080	0
# A3 alt	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)				
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	311	14080	0
# A5	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj =	1000 hours	312	14120	0
	RSH Resistance to Solder Heat	JESD22-A111				
# C8 # C10	SD Solderability	260 °C ± 5 °C J-STD-002	10 s	269 19	8070	0
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[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

2,68E+09
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